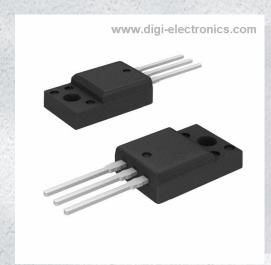


FDPF33N25T Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number FDPF33N25T-DG

Manufacturer onsemi

Manufacturer Product Number FDPF33N25T

Description MOSFET N-CH 250V 33A TO220F

Detailed Description N-Channel 250 V 33A (Tc) 37W (Tc) Through Hole T

O-220F-3



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

| Manufacturer Product Number: | Manufacturer: |
|---|---|
| FDPF33N25T | onsemi |
| Series: | Product Status: |
| UniFET™ | Active |
| FET Type: | Technology: |
| N-Channel | MOSFET (Metal Oxide) |
| Drain to Source Voltage (Vdss): | Current - Continuous Drain (Id) @ 25°C: |
| 250 V | 33A (Tc) |
| Drive Voltage (Max Rds On, Min Rds On): | Rds On (Max) @ ld, Vgs: |
| 10V | 94mOhm @ 16.5A, 10V |
| Vgs(th) (Max) @ ld: | Gate Charge (Qg) (Max) @ Vgs: |
| 5V @ 250μA | 48 nC @ 10 V |
| Vgs (Max): | Input Capacitance (Ciss) (Max) @ Vds: |
| ±30V | 2135 pF @ 25 V |
| FET Feature: | Power Dissipation (Max): |
| | 37W (Tc) |
| Operating Temperature: | Mounting Type: |
| -55°C ~ 150°C (TJ) | Through Hole |
| Supplier Device Package: | Package / Case: |
| TO-220F-3 | TO-220-3 Full Pack |
| Base Product Number: | |
| FDDF33 | |

Environmental & Export classification

8541.29.0095

| RoHS Status: | Moisture Sensitivity Level (MSL): |
|------------------|-----------------------------------|
| ROHS3 Compliant | Not Applicable |
| REACH Status: | ECCN: |
| REACH Unaffected | EAR99 |
| HTSUS: | |



MOSFET - N-Channel, UniFET™

250 V, 33 A, 94 m Ω

FDPF33N25T

Description

UniFET MOSFET is **onsemi**'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on–state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

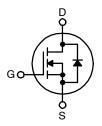
Features

- $R_{DS(on)} = 94 \text{ m}\Omega \text{ (Max.)} @ V_{GS} = 10 \text{ V}, I_D = 16.5 \text{ A}$
- Low Gate Charge (Typ. 36.8 nC)
- Low C_{rss} (Typ. 39 pF)
- 100% Avalanche Tested

Applications

- PDP TV
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

| V _{DSS} | R _{DS(on)} MAX | I _D MAX | |
|------------------|-------------------------|--------------------|--|
| 250 V | 94 mΩ @ 10 V | 33 A | |



N-Channel MOSFET

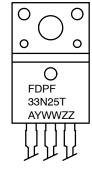


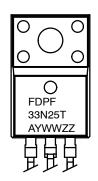
TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT



TO-220-3LD LF (LG-formed) CASE 340BL

MARKING DIAGRAM





FDPF33N25T

= Specific Device Code

YWW

1

= Assembly Location= Date Code (Year & Week)

ZZ

= Assembly Lot

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

| Symbol | Parameter | | FDPF33N25T FDPF33N25TRDTU | Unit |
|----------------------------------|--|-------------------|------------------------------|-----------|
| V_{DSS} | Drain-Source Voltage | | 250 | V |
| I _D | Drain Current $ \begin{array}{c} - \text{ Continuous } (T_C = 25^{\circ}\text{C}) \\ - \text{ Continuous } (T_C = 100^{\circ}\text{C}) \end{array} $ | | 33* 20.4* | A A |
| I _{DM} | Drain Current | - Pulsed (Note 1) | 132* | Α |
| V _{GSS} | Gate-Source Voltage | | ±30 | V |
| E _{AS} | Single Pulsed Avalanche Energy (Note 2) | | 918 | mJ |
| I _{AR} | Avalanche Current (Note 1) | | 33 | Α |
| E _{AR} | Repetitive Avalanche Energy (Note 1) | | 23.5 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | | 4.5 | V/ns |
| P _D | Power Dissipation (T _C = 25°C) – Derate Above 25°C | | 37 0.29 | W W/°C |
| T _{J,} T _{STG} | Operating and Storage Temperature Range | | -55 to +150 | °C |
| TL | Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds | | 300 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality stresses exceeding those listed in the Maximum Hatings table may damage it should not be assumed, damage may occur and reliability may be affected. *Drain current limited by maximum junction temperature.
1. Repetitive rating: pulse–width limited by maximum junction temperature.
2. L = 1.35 mH, $I_{AS} = 33$ A, $V_{DD} = 50$ V, $V_{DD} = 25$ V_{DSS} , starting $V_{DSS} = 25$ C.
3. $V_{DD} = 25$ $V_{DSS} = 25$ V_{DS

THERMAL CHARACTERISTICS

| Symbol | Parameter | FDPF33N25T FDPF33N25TRDTU | Unit |
|-----------------|---|------------------------------|------|
| $R_{	heta JC}$ | Thermal Resistance, Junction-to-Case, Max. | 3.4 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 62.5 | °C/W |

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|----------------------------------|---|---|-----|--------|---------|--------------------------|
| OFF CHAR | ACTERISTICS | | | | • | • |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_J = 25^{\circ}\text{C}$ | 250 | _ | _ | V |
| $\Delta BV_{DSS} / \Delta T_{J}$ | Breakdown Voltage Temperature Coefficient | I_D = 250 μ A, Referenced to 25°C | - | 0.25 | - | V/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 250 V, V _{GS} = 0 V V _{DS} = 200 V, T _C = 125°C | | - - | 1 10 | μ Α μ Α |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 30 V, V _{DS} = 0 V | - | - | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{V}$ | - | - | -100 | nA |
| ON CHARA | ACTERISTICS | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 3.0 | - | 5.0 | V |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} = 10 V, I _D = 16.5 A | - | 0.077 | 0.094 | Ω |
| 9FS | Forward Transconductance | V _{DS} = 40 V, I _D = 16.5 A | - | 26.6 | _ | S |
| DYNAMIC (| CHARACTERISTICS | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz | - | 1640 | 2135 | pF |
| C _{oss} | Output Capacitance | | - | 330 | 430 | pF |
| C _{rss} | Reverse Transfer Capacitance | 1 | - | 39 | 59 | pF |
| SWITCHIN | G CHARACTERISTICS | | | | | |
| t _{d(on)} | Turn-On Delay Time | $V_{DD} = 125 \text{ V}, I_D = 33 \text{ A}, V_{GS} = 10 \text{ V},$ | - | 35 | 80 | ns |
| t _r | Turn-On Rise Time | $R_G = 25 \Omega$ (Note 4) | - | 230 | 470 | ns |
| t _{d(off)} | Turn-Off Delay Time | 1 | - | 75 | 160 | ns |
| t _f | Turn-Off Fall Time | 1 | - | 120 | 250 | ns |
| Qg | Total Gate Charge | V _{DS} = 200 V, I _D = 33 A, V _{GS} = 10 V | - | 36.8 | 48 | nC |
| Q _{gs} | Gate-Source Charge | (Note 4) | - | 10 | _ | nC |
| Q _{gd} | Gate-Drain Charge | 1 | - | 17 | _ | nC |
| DRAIN-SO | URCE DIODE CHARACTERISTICS AND MAX | IMUM RATINGS | | | - | |
| IS | Maximum Continuous Drain-Source Diode Forward Current | | - | _ | 33 | Α |
| I _{SM} | Maximum Pulsed Drain-Source Diode Forwar | d Current | - | - | 132 | Α |
| V_{SD} | Drain-Source Diode Forward Voltage | V _{GS} = 0 V, I _S = 33 A | - | - | 1.4 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0 V, I _S = 33 A, | - | 220 | - | ns |
| Q _{rr} | Reverse Recovery Charge | dI _F /dt = 100 A/μs | _ | 1.71 | - | μC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

PACKAGE MARKING AND ORDERING INFORMATION

| Part Number | Top Mark | Package | Shipping |
|----------------|------------|---|-------------------|
| FDPF33N25T | FDPF33N25T | TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT | 1000 Units / Tube |
| FDPF33N25TRDTU | FDPF33N25T | TO-220-3LD LF (LG-formed) CASE 340BL | 800 Units / Tube |

TYPICAL PERFORMANCE CHARACTERISTICS

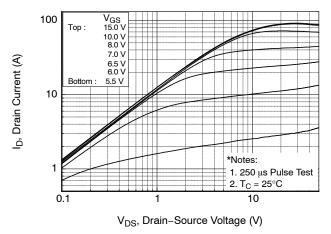


Figure 1. On-Region Characteristics

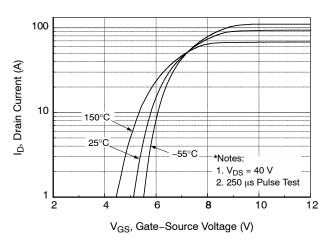


Figure 2. Transfer Characteristics

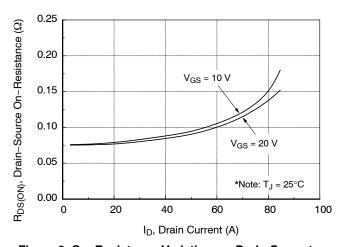


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

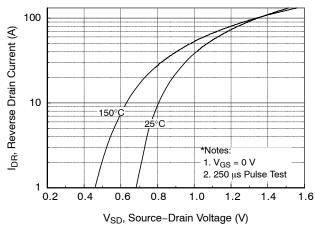


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

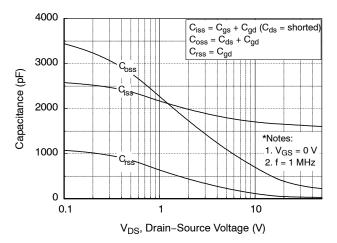


Figure 5. Capacitance Characteristics

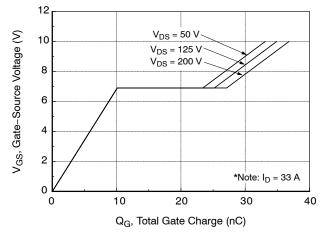
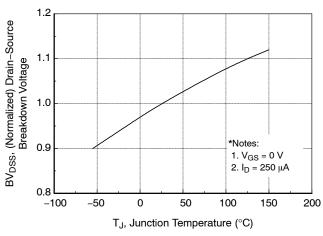


Figure 6. Gate Charge Characteristics

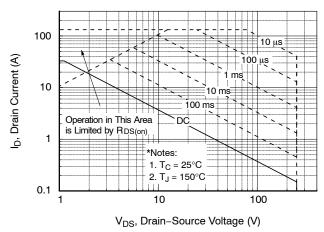
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)



3.0 R_{DS(ON)}, (Normalized) Drain-Source 2.5 On-Resistance 2.0 1.5 1.0 *Notes: 0.5 1. V_{GS} = 10 V 2. I_D = 16.5 A 0.0 _____ -50 100 150 200 T_J, Junction Temperature (°C)

Figure 7. Breakdown Voltage Variation vs.
Temperature

Figure 8. On-Resistance Variation vs. Temperature



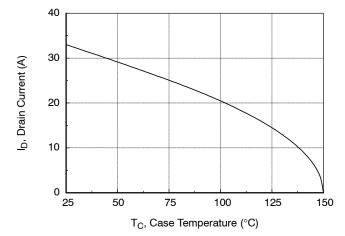


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

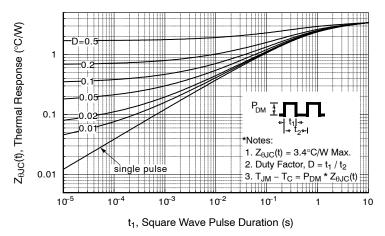


Figure 11. Transient Thermal Response Curve

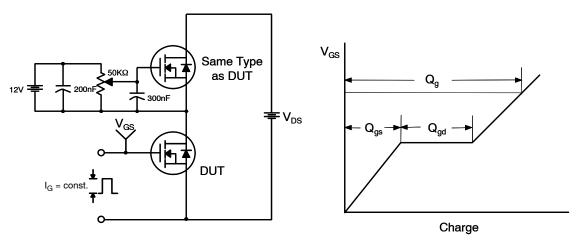


Figure 12. Gate Charge Test Circuit & Waveform

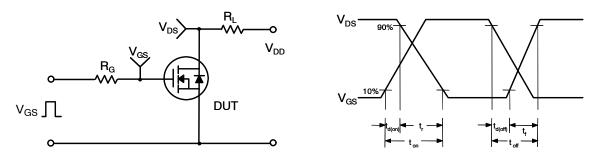


Figure 13. Resistive Switching Test Circuit & Waveforms

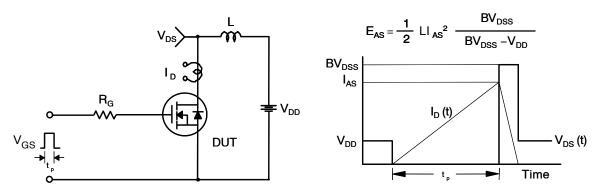
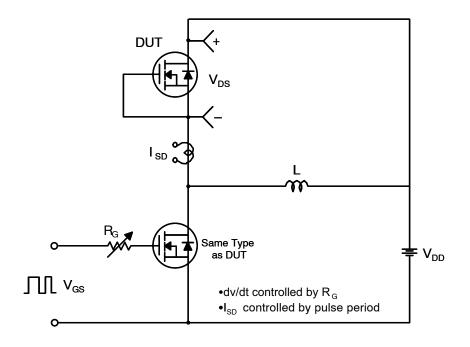


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



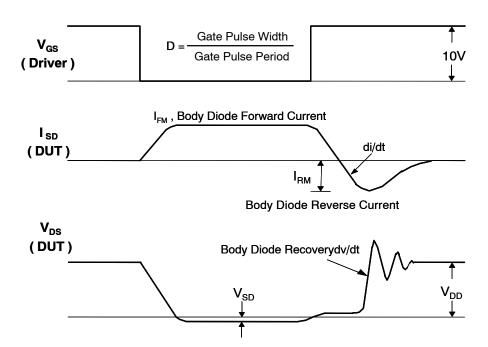
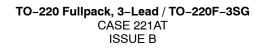


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

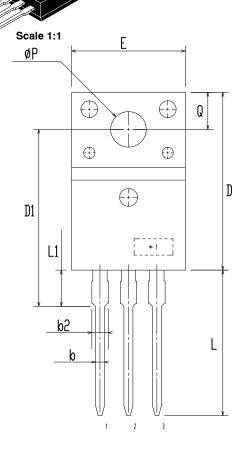


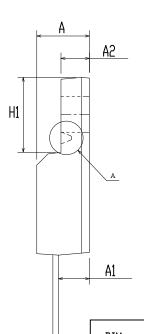
MECHANICAL CASE OUTLINE

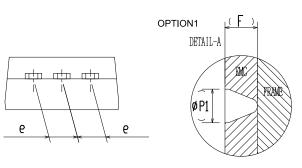
PACKAGE DIMENSIONS



DATE 19 JAN 2021







| DIM | LITE | HILLIHITING | | |
|-------|-------|-------------|-------|--|
| ויונע | MIN | NDM | MAX | |
| Α | 4.50 | 4.70 | 4.90 | |
| A1 | 2.56 | 2.76 | 2.96 | |
| A2 | 2.34 | 2.54 | 2.74 | |
| b | 0.70 | 0.80 | 0.90 | |
| b2 | ~ | 2 | 1.47 | |
| С | 0.45 | 0.50 | 0.60 | |
| D | 15.67 | 15.87 | 16.07 | |
| D1 | 15.60 | 15.80 | 16.00 | |
| E | 9.96 | 10.16 | 10.36 | |
| е | 2.34 | 2.54 | 2.74 | |
| F | ~ | 0.84 | 2 | |
| H1 | 6.48 | 6.68 | 6.88 | |
| L | 12.78 | 12.98 | 13.18 | |
| L1 | 3.03 | 3.23 | 3.43 | |
| ØΡ | 2.98 | 3.18 | 3,38 | |
| ø P1 | ~ | 1.00 | ~ | |
| Q | 3,20 | 3.30 | 3.40 | |
| | | | | |

MILLIMITERS

NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.
- C. OPTION 1 WITH SUPPORT PIN HOLE OPTION 2 NO SUPPORT PIN HOLE

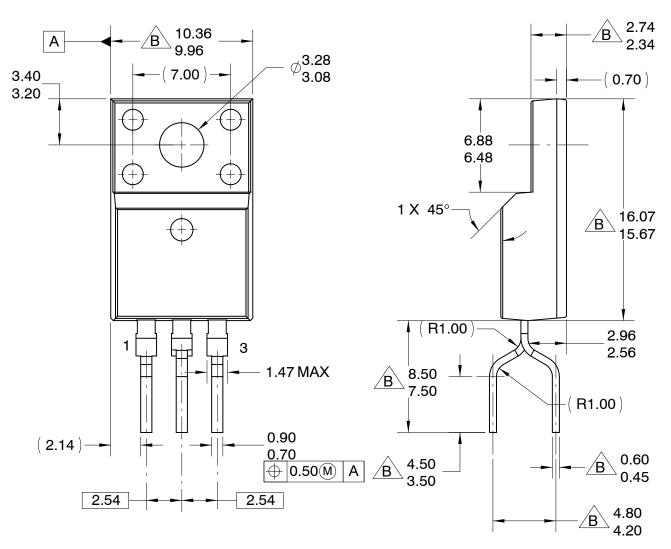
| DOCUMENT NUMBER: | | Electronic versions are uncontrolled except when accessed directly from the Document Repository Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. | | |
|------------------|---------------------------------------|--|-------------|--|
| DESCRIPTION: | TO-220 FULLPACK, 3-LEAD / TO-220F-3SG | | PAGE 1 OF 1 | |

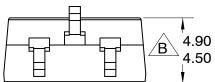
onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

TO-220-3LD LF CASE 340BL ISSUE O

DATE 31 AUG 2016





NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- B DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.

| DOCUMENT NUMBER: | 98AON13844G | Electronic versions are uncontrolled except when accessed directly from the Document Repos Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. | |
|------------------|---------------|---|-------------|
| DESCRIPTION: | TO-220-3LD LF | | PAGE 1 OF 1 |

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that onsemi was negligent regarding the design or manufacture of the part. onsemi is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales



OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we striciy control the quality of products and services. Welcome your RFQ to Email: Info@DiGi-Electronics.com

















Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com